



Material Content Data Sheet



Sales Product Name		SPA20N60C3		Issued		2. November 2015			
MA#		MA001425758							
Package		PG-TO220-3-253		Weight*		2136.91 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	12.312	0.58	0.58	5762	5762	
leadframe	non noble metal	iron	7439-89-6	1.431	0.07		669		
	inorganic material	phosphorus	7723-14-0	0.429	0.02		201		
	non noble metal	copper	7440-50-8	1428.770	66.86	66.95	668614	669484	
wire	non noble metal	aluminium	7429-90-5	3.009	0.14	0.14	1408	1408	
encapsulation	organic material	carbon black	1333-86-4	3.310	0.15		1549		
	plastics	epoxy resin	-	129.105	6.04		60417		
	inorganic material	silicondioxide	60676-86-0	529.661	24.79	30.98	247863	309829	
leadfinish	non noble metal	tin	7440-31-5	21.731	1.02	1.02	10169	10169	
plating	non noble metal	nickel	7440-02-0	1.786	0.08	0.08	836	836	
solder	non noble metal	antimony	7440-36-0	0.537	0.03		251		
	noble metal	silver	7440-22-4	1.342	0.06		628		
	non noble metal	tin	7440-31-5	3.489	0.16	0.25	1633	2512	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com